

THERMOSETTING FLUORINATED DIELECTRICS AND MULTILAYER
CIRCUIT BOARDS

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ABSTRACT OF THE DISCLOSURE

A dielectric film is obtained by heat curing a thermally curable fluorinated o-aminophenol polymer or oligomer based on an o-aminophenol compound and an aromatic dicarboxylic acid compound, at least one of which is mono- or poly-fluorinated, and having thermosetting groups at both ends that undergo cross-linking reaction upon thermal treatment. The dielectric film is employed in multilayer circuit boards.